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TECHSIM INSIGHT 2027 · EXPERT SEMINAR

Power semiconductors

From characteristics to applications

WHEN	**Thursday, 4 February 2027, 9:00–16:00**
WHERE	**TITC, Purkyňova 125, Brno-Královo Pole**
FEE	**CZK 3,000 / person · 30 participants**

The seminar brings together developers and manufacturers of power semiconductors, diodes, modules and LEDs with converter designers and users of power electronics. It shows how measurement data, simulation and reliability testing support component selection and deployment in industrial products.

What the seminar connects

- Development of the Czech and Slovak semiconductor ecosystem
- Thermal-path characterization, power cycling and manufacturing quality control
- Experience from RICE, EIÚ SAV and STU FEI research institutions
- Design and verification of power PCBs and converters in HyperLynx
- Power architectures for e-mobility, data centers and AI computing systems
- Thermal design in FLOEFD and system integration in Amesim using FMI/FMU

Reserve your place

The registration fee is CZK 3,000 per person. Capacity is limited to 30 participants. Refreshments will be provided.

www.techsim.cz/konference

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TECHSIM INSIGHT 2027 · POWER SEMICONDUCTORS

Seminar programme

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Morning session

9:00–12:20 · trends, research and experience

9:00–9:10	Opening and technical introduction	TechSim
9:10–9:40	The future of the Czech semiconductor ecosystem and power devices	SemiCZ / WBU
9:40–10:10	Power semiconductors, pilot lines and the European value chain	SK Chips / STU FEI
10:10–10:40	Use of Siemens DI and Siemens EDA products in power semiconductor design, manufacturing and testing	Siemens DI/EDA
10:40–11:00	Coffee break	
11:00–11:20	Measurement of power-semiconductor characteristics	UWB RICE
11:20–11:40	Semiconductor-device development and testing experience	EIÚ SAV, v. v. i.
11:40–12:00	HyperLynx and the latest power-electronics trends: EVs, data centers and AI infrastructure	Siemens EDA
12:00–12:20	From characteristics to applications: an overview of Siemens solutions	TechSim
12:20–13:20	**Lunch and networking**	

Afternoon technical session

13:20–16:00 · measurement, simulation and applications

13:20–13:45	Characterization, power cycling and production quality control: T3STER SI, Power Tester and Quality Tester	TechSim
13:45–14:10	Simcenter PSIM: semiconductor selection and power-converter design	Siemens
14:10–14:35	Simcenter SimLab: packages, power modules, PCBs and thermomechanical reliability	Siemens
14:35–14:55	Coffee break	
14:55–15:20	Simcenter FLOEFD: thermal analysis and cooling design for power electronics	TechSim
15:20–15:40	Simcenter Amesim: converter system integration, connection with HyperLynx and FMI/FMU	TechSim
15:40–15:50	Connecting measurement and simulation in one development process	TechSim
15:50–16:00	Panel discussion and closing remarks	All speakers

ENGINEERING FLOW **Device > Characteristics > Reliability > Converter > Thermal design > Application**

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